

# 40 A Stackable Synchronous Buck Regulator

## NCP3296

The NCP3296, a highly-efficient stackable synchronous buck regulator, is capable of operating with an input range from 3 V to 18 V and supporting up to 40 A continuous load currents. Higher output currents can be achieved by 2, 3, or 4 parallel NCP3296 devices operating as an interleaved multi-phase buck regulator.

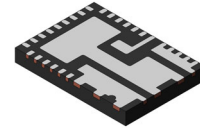
The NCP3296 utilizes fixed-frequency current-mode control to provide accurate voltage regulation and fast transient response. Flexible programming of function and parameters supports multiple applications.

### Features

- $V_{IN}$ : 3 – 18 V with Input Feed-Forward
- $V_{OUT}$ : 0.5 – 5.5 V with Remote Output Voltage Sense
- 40 A Continuous Output Current – Stackable to 160 A
- Fixed Frequency Current Mode Control
- Integrated 5 V LDO or External Supply
- Enable with Programmable VIN UVLO
- Programmable Boot-Up Voltage
- Programmable Soft-Start
- Pre-Bias Start-Up
- Programmable Current Limit
- Power Good Indicator
- Selectable Protection Mode (Latch-off or Hiccup)
- Under-Voltage and Over-Voltage Protection
- Output Discharge in Shutdown
- 150°C Operating Junction Temperature

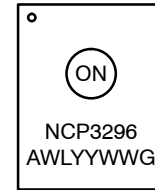
### Typical Applications

- Networking – Routers and Switches
- Telecom Digital Baseband
- Telecom Radio Unit
- Server and Desktop Computers, Notebooks, Gaming
- High Density Power Solutions
- DC/DC Modules
- General Purpose POL Regulator



WQFN34 5x7, 0.5P  
CASE 510CL

### MARKING DIAGRAM



NCP3296 = Specific Device Code  
 A = Assembly Location  
 WL = Wafer Lot  
 YY = Year  
 WW = Work Week  
 G = Pb-Free Designator

### ORDERING INFORMATION

See detailed ordering and shipping information on page 23 of this data sheet.

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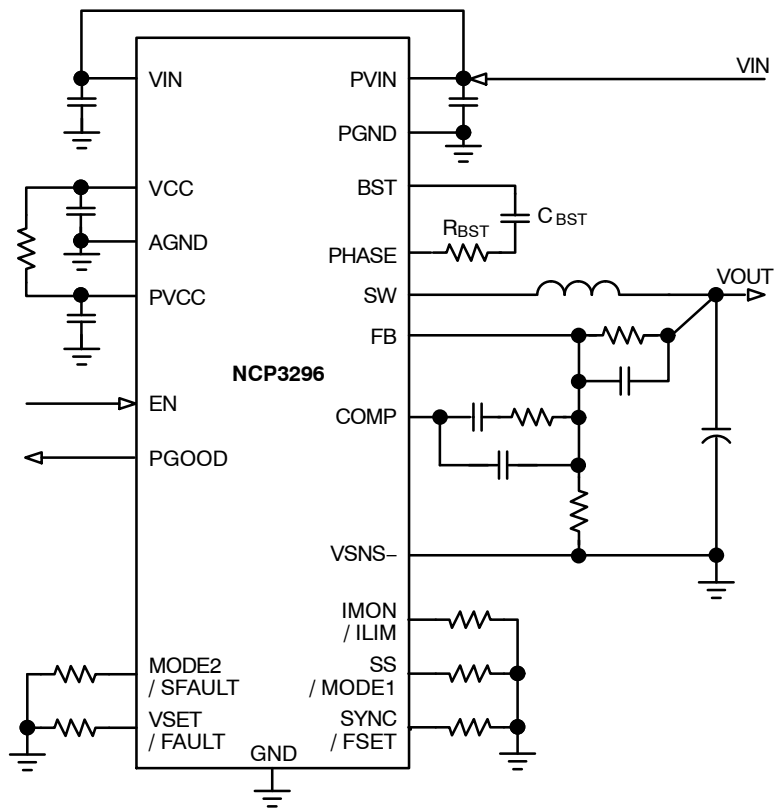


Figure 1. Typical 12 V<sub>IN</sub>, 40 A Application Circuit for Single Input Supply (LDO Enabled)

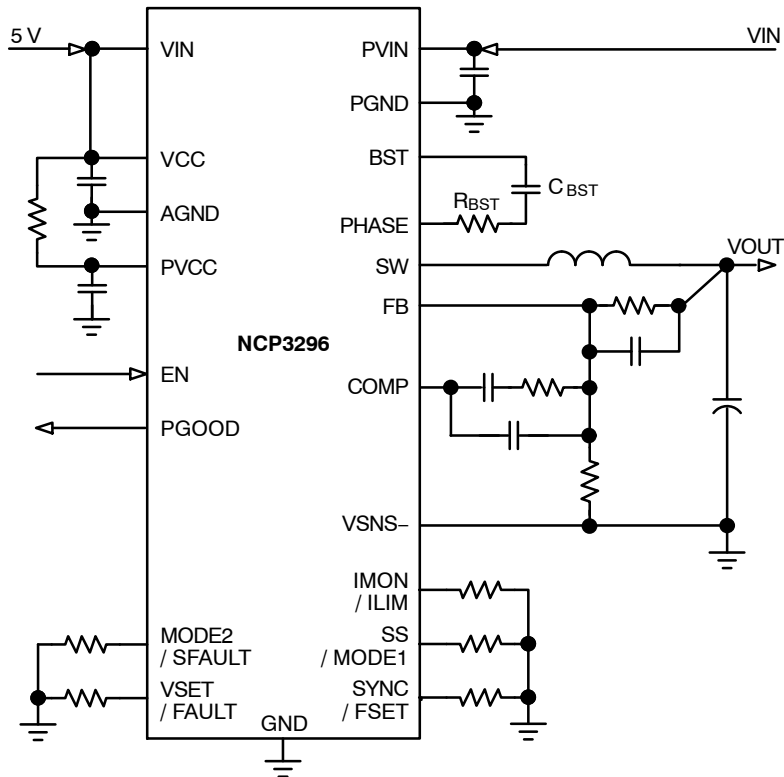


Figure 2. Typical 12 V<sub>IN</sub>, 40 A Application Circuit with External 5 V VCC Supply (LDO Disabled)

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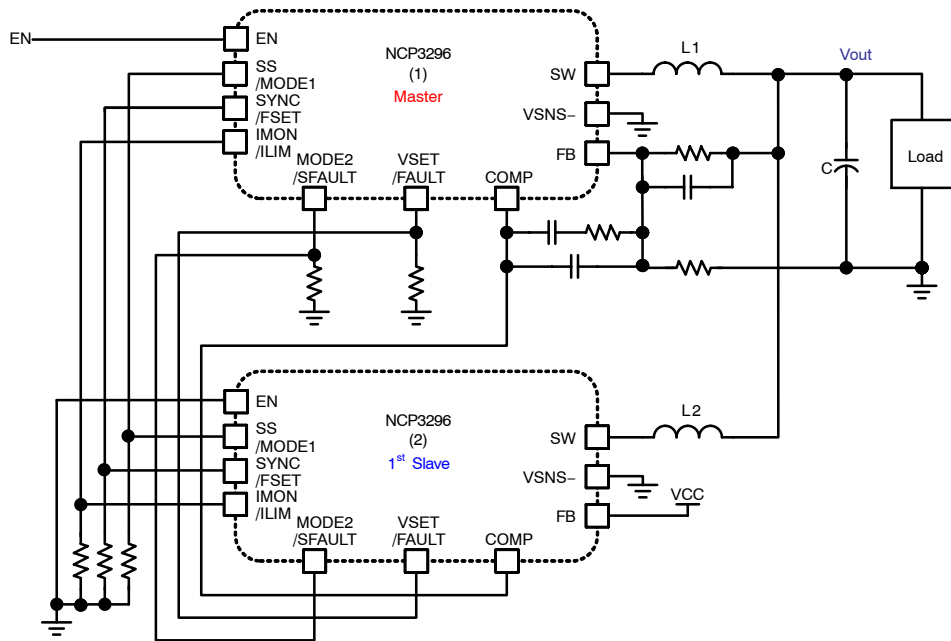


Figure 3. Typical 80 A Application Circuit with 2 Parallel NCP3296

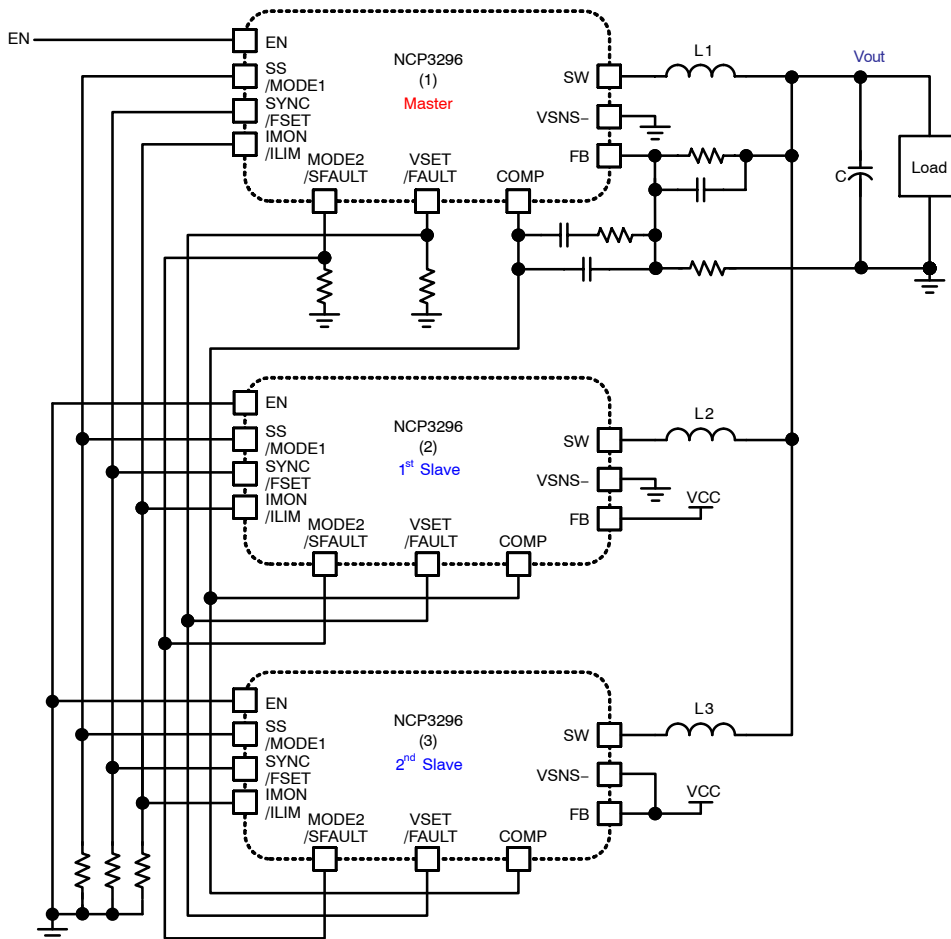


Figure 4. Typical 120 A Application Circuit with 3 Parallel NCP3296

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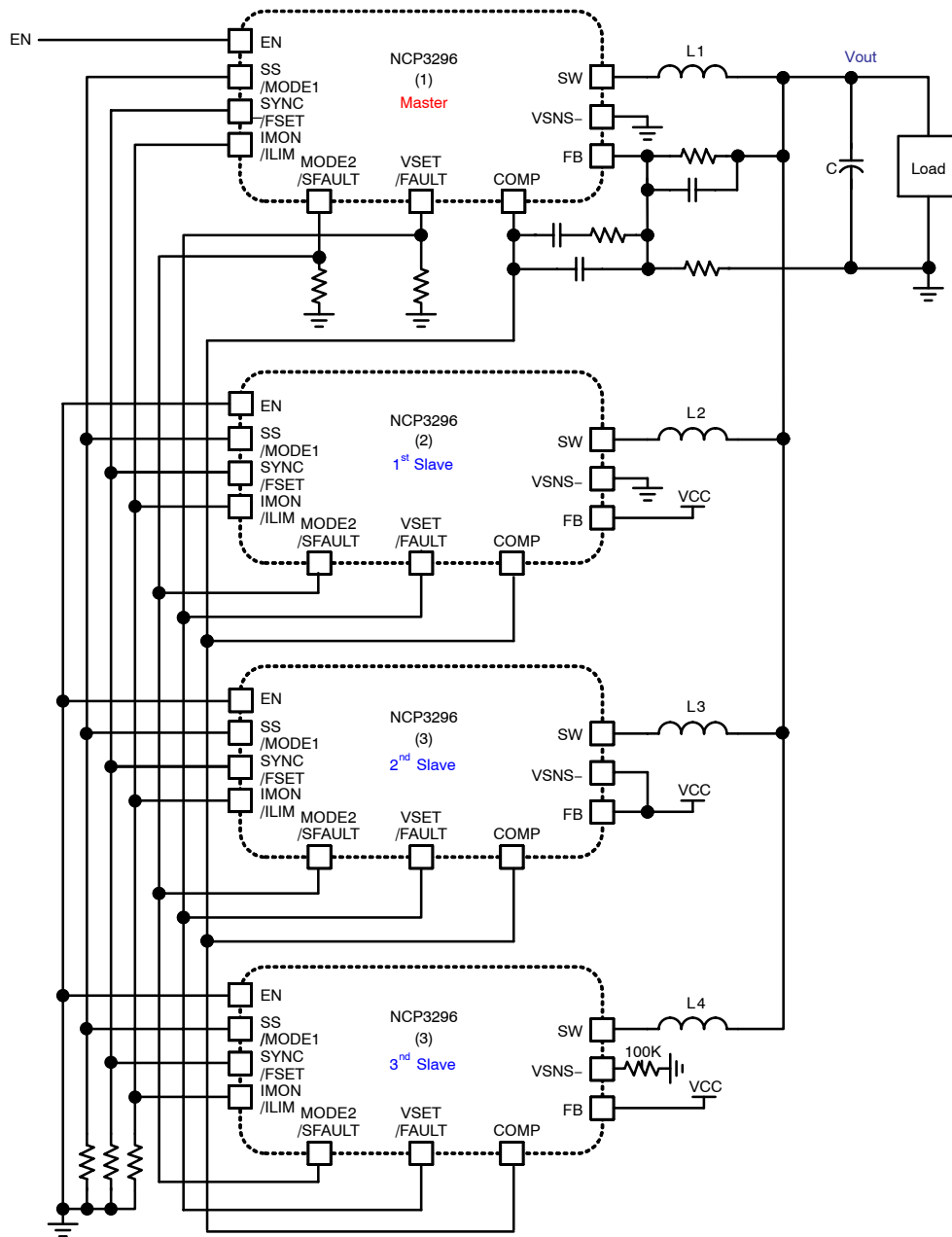


Figure 5. Typical 160 A Application Circuit with 4 Parallel NCP3296



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## PIN CONNECTIONS

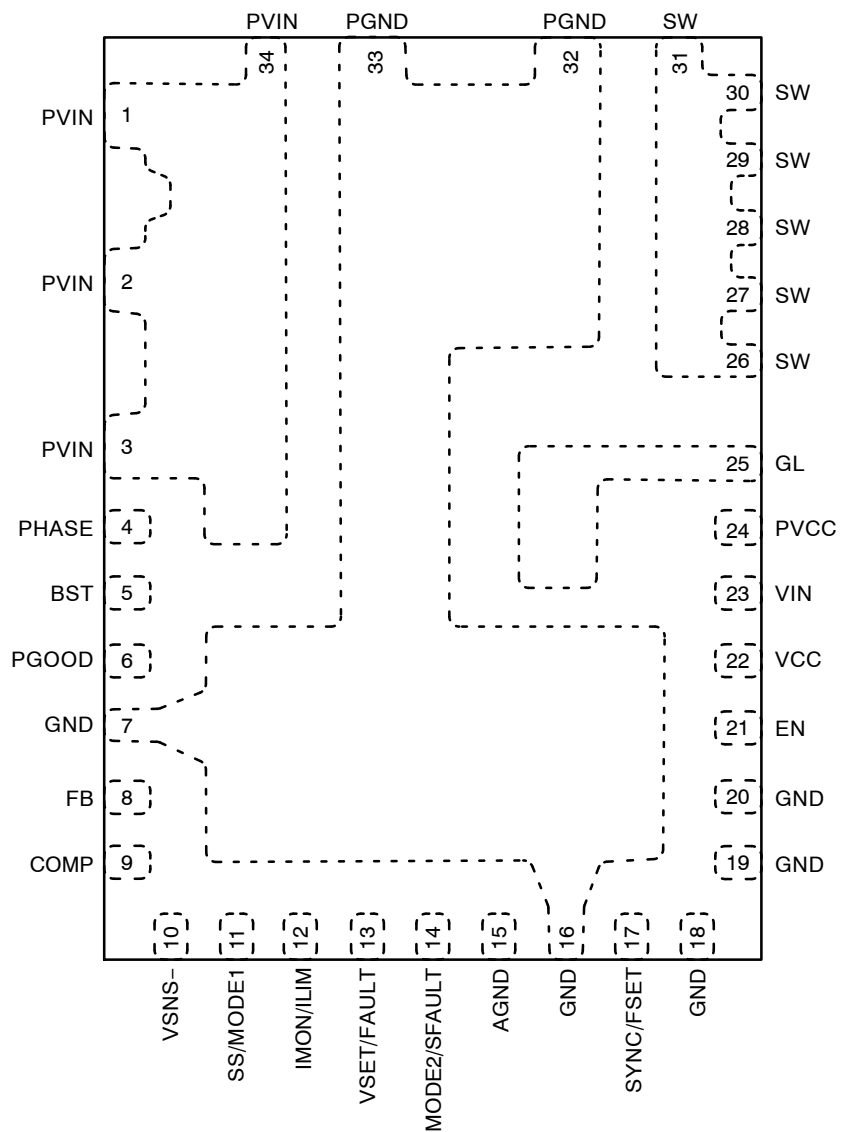


Figure 7. Pin Assignment, Top Transparent View (5 x 7 mm, 0.5 mm Pitch)

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## PIN DESCRIPTION

Pin	Name	Type	Description
1~3, 34	PVIN	Power	<b>Power Supply Input.</b> Power supply input pins of the device, which are connected to the drain of internal high-side power MOSFET. Bypass directly to PGND with $\geq 22 \mu\text{F}$ ceramic capacitors using the lowest impedance possible connections to the IC pins.
4	PHASE	Power	<b>Phase Node.</b> Provides a return path for integrated high-side gate driver, which is internally connected to the source of the high-side MOSFET.
5	BST	Power	<b>Bootstrap.</b> Provides bootstrap voltage for high-side gate driver. A $0.22 \mu\text{F}$ , 25 V ceramic capacitor is required from this pin to PHASE. A resistor ( $R_{\text{BST}}$ ) in series with capacitor ( $C_{\text{BST}}$ ) is also recommended.
6	PGOOD	Logic Output	<b>Power GOOD.</b> Open-drain output. Provides a logic high valid power good output signal, indicating the regulator's output is in the regulation window.
7, 16, 18~20, 32~33	GND PGND	Power Ground	<b>Power Ground.</b> Power supply ground pins of the device, which are connected to the source of the internal low-side power MOSFET. Must be connected to the system ground using lowest possible impedance path.
8	FB	Analog Input	<b>Feedback.</b> Inverting input to error amplifier. Also used to program the slave phase number.
9	COMP	Analog Output	<b>Compensation.</b> Output of error amplifier.
10	VSNS-	Analog Input	<b>Voltage Sense Negative Input.</b> Connect this pin to remote voltage negative sense point. Also used to program the slave phase number.
11	SS / MODE1	Analog Input	<b>Soft Start and Mode 1.</b> A 1% resistor between this pin and ground sets default soft start time, operation mode, and VOUT_SCALE_LOOP.
12	IMON / ILIM	Analog I/O	<b>IMON and Current Limit.</b> IMON voltage output/input pin. A 1% resistor between this pin and ground programs the per-phase valley current limit and protection mode.
13	VSET / FAULT	Analog I/O	<b>Boot-Up Voltage and FAULT.</b> A resistor from this pin to ground programs the boot-up voltage. Output pin of fault signal from master.
14	MODE2 / SFAULT	Analog I/O	<b>Mode 2 and SFAULT.</b> A resistor from this pin to ground programs the device operation mode and phase count. Output pin of fault signal from slave.
15	AGND	Analog Ground	<b>Analog Ground.</b> Ground of controller. Must be connected to the system ground using a low impedance single-point connection to GND/PGND.
17	SYNC / FSET	Analog I/O	<b>Synchronization Clock and Frequency Set.</b> Synchronization clock output from master. A resistor between this pin and ground programs frequency.
21	EN	Logic Input	<b>Enable.</b> High enables the controller. Input supply UVLO can be programmed at this pin with external resistor divider.
22	VCC	Power	<b>Output of LDO and Supply Voltage Input of Controller.</b> Output of LDO and bias supply input of controller. A $2.2 \mu\text{F}$ or larger ceramic capacitor bypasses this input to GND. This capacitor should be placed as close as possible to the pin.
23	VIN	Power	<b>Power Supply Input of LDO.</b> Power supply input of LDO. Use $1.0 \mu\text{F}$ or more ceramic bypass capacitor to power ground. The capacitors should be placed as close as possible to this pin. For applications using an external VCC source, connect this pin to VCC and the 5 V source.
24	PVCC	Power	<b>Supply Voltage Input of Gate Drivers.</b> A $4.7 \mu\text{F}$ , 25 V or larger ceramic capacitor bypasses this input to PGND. This capacitor should be placed as close as possible to this pin.
25	GL	Analog Output	<b>Gate of Low-Side MOSFET.</b> Directly connected with the gate of the low-side power MOSFET. No external connection is necessary.
26~31	SW	Power	<b>Switch Node.</b> Connect to the external inductor. These pins are interconnection between internal high-side MOSFET and low-side MOSFET.

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## MAXIMUM RATINGS (All voltages with respect to GND/PGND, unless otherwise specified.)

Rating (Note 1)		Symbol	Min	Max	Unit
Input Voltage		$V_{VIN}, V_{PVIN}$	-0.3	22	V
Driver Supply Voltage		$V_{PVCC}$	-0.3	6.5	V
Analog Supply Voltage to AGND		$V_{VCC}$	-0.3	6.5	V
SW, PHASE Voltage		$V_{SW}, V_{PHASE}$	-0.5, -5 (<10 ns)	25, 28 (<10 ns)	V
BST Voltage		$V_{BST}$	-0.3	30	V
BST to SW/PHASE Voltage		$V_{BST-SW}$	-0.3	6.5	V
GL Voltage		$V_{GL}$	-0.3, -2 (<50 ns)	$V_{PVCC} + 0.3$	V
VSNS- to AGND	Normal Dynamic Operation Range	$V_{SNS-}$	-0.2	0.2	V
	During Slave Configuration at Start-up		-0.2	$V_{VCC} + 0.3$	
SCL, SDA, PGOOD, ALERT# Pins			-0.3	6.5	V
Other Pins			-0.3	$V_{VCC} + 0.3$	V
GND/PGND to AGND (Note 2)		$V_{AGND}$	-0.3	0.3	V
Operating Junction Temperature		$T_J$	-40	150	°C
Storage Temperature		$T_{STG}$	-55	150	°C
Lead Temperature Soldering Reflow (Note 3)		$T_{SLD}$	260		°C
ESD, Human Body Model per ANSI/ESDA/JEDEC JS-001		$ESD_{HBM}$	2	-	kV
ESD, Charge Device Model per ANSI/ESDA/JEDEC JS-002		$ESD_{CDM}$	1.5	-	kV
Maximum Latch-up Current Rating, 150°C, per JEDEC JESD78		$I_{LU}$	-100	100	mA
Moisture Sensitivity Level per IPC/JEDEC Standard: J-STD-020A		MSL	1		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Refer to ELECTRICAL CHARACTERISTICS, RECOMMENDED OPERATING RANGES and/or APPLICATION INFORMATION for Safe Operating parameters.
2. GND and PGND are internally connected. AGND requires PCB connection to GND.
3. For information, please refer to our Soldering and Mounting Techniques Reference Manual, SOLDERRM/D

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Air (Note 4)	$R_{\theta JA}$	14.6	°C/W
Thermal Resistance, MOSFET Junction-to-PCB	$R_{\theta JB}$	1.5	°C/W

4. Values are based upon **onsemi** Evaluation Board of 2 oz. copper thickness and FR4 PCB substrate.

## RECOMMENDED OPERATING CONDITIONS

Rating	Symbol	Min	Max	Unit
Input Voltage (Note 5)	$V_{VIN}, V_{PVIN}$	3	18	V
Output Voltage	$V_{OUT}$	0.5	5.5	V
Output Current, Continuous	$I_{OUT}$	0	40	A
SW Voltage, Peak (Note 6)	$V_{SW\ pk}$	-	22	V
Junction Temperature	$T_J$	-40	150	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Operation at  $<4.5V_{IN}$  requires external 5 V supply be applied to the VIN and VCC pins per Figure 2.
6. Operation above  $V_{SW\ pk}$  may result in reduced IMON accuracy ( $V_{IMON\ ACY}$ ).



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## ELECTRICAL CHARACTERISTICS (VIN = PVIN = 12 V, VOUT = 1.0 V, FSW = 500 kHz, circuit of Figure 1.

Typical values: TA = TJ = 25°C, min/max: -40°C ≤ TJ ≤ 150°C, unless otherwise specified.)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
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### SUPPLY CURRENT

Input Shutdown Current	EN = 0, VIN = PVIN, LDO Enabled	IPVIN_SD	-	7	9	mA
	EN = 0, LDO Disabled, VCC = 5.2 V			375	480	
Input Quiescent Current	12 VIN, VIN = PVIN, no switching	IPVIN_Q	-	10	17	mA
	18 VIN, VIN = PVIN, no switching			10	17	

### INTERNAL LINEAR REGULATOR

LDO Output Voltage	6 V ≤ VVIN ≤ 18 V, EN = 0, I_VCC = 0 – 50 mA external	VCC	4.8	5.0	5.3	V
LDO Drop-Out Voltage	VVIN = 5 V, EN = 0, I_VCC = 50 mA external	VDO	-	-	250	mV
LDO Current Limit	VVIN = 5.4 V, EN = 0	ICC_MAX	95	-	-	mA
VCC UVLO Threshold	VVCC rising	VCC_OK	-	4.4	4.5	V
	VVCC falling	VCC_UV	4.0	4.2	-	
	Hysteresis	VCC_HYS	-	200	-	mV

### ENABLE

EN On Threshold	EN rising	VEN_TH	1.08	1.20	1.32	V
Hysteresis Resistance		RHYS	-	40	-	kΩ
Hysteresis Current		IEN_HYS	-	5.2	-	μA
EN Input Leakage Current	EN = 1 V	IEN_LKG	-	-	0.5	μA

### DEFAULT PROGRAMMING /DETECTION

Source Current from Pin	SS/MODE1 pin	ISS	9.7	10	10.3	μA
	IMON/ILIM pin	ILIM	9.7	10	10.3	
	VSET/FAULT pin	IVSET	9.7	10	10.3	
	MODE2/SFAULT pin	IADDR	9.7	10	10.3	
	SYNC/FSET pin	IFSW	9.7	10	10.3	

### PWM MODULATOR

Minimum On-Time (Note 7)		TON_MIN	-	35	55	ns
Minimum Off-Time (Note 7)		TOFF_MIN	-	275	300	ns

### VOLTAGE ERROR AMPLIFIER

Open Loop DC Gain (Note 7)		AVEA	-	80	-	dB
Unity Gain Bandwidth (Note 7)		GBWEA	-	12	-	MHz
Slew Rate (Note 7)		SR_COMP	-	15	-	V/μs
Output Source/Sink Current	VCOMP = 1.2 V	ICOMP	10	20	-	mA
COMP Voltage Swing	ICOMP(SOURCE) = 2 mA	VCOMP_H	3.1	3.4	-	V
	ICOMP(SINK) = 2 mA	VCOMP_L	-	0.55	0.78	V
FB Bias Current	VFB = 1.00 V	IFB	-150	-	150	nA

### CURRENT SENSE AMPLIFIER

Closed Loop DC Gain		AVCA	-	-10	-	mV/A
-3dB Gain Bandwidth (Note 7)		BWCA	-	7	-	MHz

### REFERENCE VOLTAGE

Reference Voltage (Note 7)	Programmable Range, RSS/MODE1 = 10.0 kΩ	VFB	0.50	-	1.25	V
	Resolution, RSS/MODE1 = 10.0 kΩ		-	50	-	mV
	Setting/Value		Determined by RVSET/FAULT			V

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Typical values: TA = TJ = 25°C, min/max: -40°C ≤ TJ ≤ 150°C, unless otherwise specified.) (continued)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
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### REFERENCE VOLTAGE

Reference Voltage Accuracy	0°C ≤ TJ ≤ 125°C	RVSET = 10.0 kΩ	VFB_ACCY	494	500	506	mV
		RVSET = 82.5 kΩ		994	1000	1006	
		RVSET = open		1243	1250	1257	
	-40°C ≤ TJ ≤ 150°C	RVSET = 10.0 kΩ		492	500	508	
		RVSET = 82.5 kΩ		992	1000	1008	
		RVSET = open		1241	1250	1259	

### CYCLE-BY-CYCLE CURRENT LIMIT

Valley Current Limit (Note 7)	Threshold Range		IVLY	10	-	60	A	
	Resolution	10 ≤ A IVLY < 20 A		-	2	-		
		20 ≤ A IVLY < 60 A		-	4	-		
	Setting			Determined by RIMON/ILIM				
	Accuracy, IVLY ≥ 20 A, 0°C < TJ < 125°C			-5	-	10		%
	Accuracy, IVLY ≥ 20 A, -40°C < TJ < 150°C			-10	-	15		%
Over-Current Protection De-Bounce Time (Note 7)	Consecutive cycles before fault state entry		TD_VLY	-	32 / FSW	-	s	
Negative Current Limit Threshold (Note 7)	Low-Side FET		ILIM_NEG	-	45	-	A	

### SWITCHING FREQUENCY

Switching Frequency, 1 Phase	Programmable Range		FSW	200	-	2000	kHz
	Resolution	200 ≤ FSW < 400 kHz		-	50	-	
		400 ≤ FSW < 1,000 kHz		-	100	-	
		1,000 ≤ FSW ≤ 2,000 kHz		-	200	-	
	Setting			Determined by RSYNC/FSET			
	Accuracy			-10		10	

### SYNCHRONIZATION (SYNC/FSET PIN)

Logic High Output Voltage, Master	ISYNC = 4 mA (sourcing)	VOH_SYNC	VCC - 0.3	-	-	V
Logic Low Output Voltage, Master	ISYNC = -4 mA (sinking)	VOL_SYNC		-	0.3	V
Logic High Input Voltage, Slave		VIH_SYNC	VCC - 1.0	-	-	V
Logic Low Input Voltage, Slave		VIL_SYNC	-	-	1.0	V
Hysteresis (Slave)			-	1.3	-	V
Input Current Bias, Slave		IIN_SYNC	-0.5	-	0.5	μA
Input Capacitance, Slave (Note 7)			-	5.0	-	pF

### MASTER/SLAVE FAULTS (FAULT, SFAULT PINS)

Tri-State Voltage	IFault = ISFault = 0	VFLT_3ST	1.7	2.0	2.3	V
Tri-State Source Current	VFault = VSFault = 1.6 V	I3ST_UP	230	300	370	μA
Tri-State Sink Current	VFault = VSFault = 2.4 V	I3ST_DN	80	100	120	μA
Output Pull-Up Impedance	IFault = ISFault = 2 mA (sourcing)	RFLT_HI	25	36	60	Ω
Output Pull-Down Impedance	IFault = ISFault = -2 mA (sinking)	RFLT_LO	240	260	300	Ω
Input Logic Low Threshold		VFLT_IL	-	-	0.4	V
Input Logic High Threshold		VFLT_IH	VCC - 1.5	-	-	V

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Typical values: TA = TJ = 25°C, min/max: -40°C ≤ TJ ≤ 150°C, unless otherwise specified.) (continued)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
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### SOFT START

Soft Start Delay Time	Setting	TON_DLY	-	1	-	ms
	Accuracy		-0.8	-	1.4	
Soft Start Time (0-VFB)	Programmable Range	TSS	1	-	20	ms
	Resolution		1, 3, 5, 10, 15, or 20			
	Setting		Determined by RSS/MODE1			
	Accuracy		Valid RVSET values ≥ 1.00 VOUT	-20	-	20
	Valid RVSET values < 1.00 VOUT	-25	-	25		

### DISABLE / SHUTDOWN

Output Fall Time OVP, (VFB=0)	Setting	TOFF	-	5	-	ms
	Accuracy (for valid RVSET/FAULT values)		-20	-	20	
Output Discharge Load	SW to GND	RSW_D	-	5	-	kΩ

### INPUT VOLTAGE PROTECTION

Input Over-Voltage Protection	Threshold Range, VPVIN rising	VPVIN_OVP	-	18	-	V
	Accuracy		-5	-	5	
	Hysteresis	VPVIN_HYS	-	200	-	mV
	De-Bounce Time	TD_VINOV	-	1	-	μs
Input UVLO Threshold, Rising	Threshold (VPVIN)	VPVIN_ON	-	3.0	-	V
	Accuracy		-6	-	5	
Input UVLO Threshold, Falling	Threshold (VPVIN)	VPVIN_OFF	-	2.5	-	V
	Accuracy		-6	-	5	

### OUTPUT VOLTAGE PROTECTION

Output Over-Voltage Fault Threshold (FB to VSNS-, Rising FB)	Threshold	VOVP_TH	-	121	-	% VFB
	Accuracy		-2	-	2	
	Hysteresis		-	25	-	
	De-Bounce Time	TD_OVP	-	1	-	μs
Output Under-Voltage Fault Threshold (FB to VSNS-, Falling FB)	Threshold	VUVP_TH	-	20	-	% VFB
	Accuracy		-3.5	-	2	
	Hysteresis		-	1	-	
	De-Bounce Time	TD_UVP	-	1	-	μs
Absolute Over-Voltage Threshold during Soft Start (FB to VSNS-)	Threshold, rising	VOV_A	2.02	2.20	2.38	V
	Hysteresis	VOV_HYS	-	25	-	mV

### THERMAL PROTECTION

Thermal Shutdown Threshold (Note 7)	TJ rising	TSD	160	170	-	°C
Restart Temperature Threshold (Note 7)	TJ falling	TRST	-	155	-	°C

### IMON

Output Offset Voltage	IOUT = 0 A	VIMON_0	-	1.00	-	V
Output Voltage Gain	VIMON = [1.00 + (0.015625 * IOUT)] V	VIMON_I	-	15.625	-	mV/A
Output Accuracy (Note 7)	IOUT = 40 A	VIMON_ACY	-	±6	-	%
	IOUT = 25 A		-	±8	-	
	IOUT = 10 A		-	±12	-	

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Typical values: TA = TJ = 25°C, min/max: -40°C ≤ TJ ≤ 150°C, unless otherwise specified.) (continued)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
<b>POWER GOOD (AS A PERCENTAGE OF VOUT)</b>						
PGOOD Assertion (VOUT Rising)	Threshold	VPG_ON	-	90	-	%VFB
	Accuracy		-2	-	2	
PGOOD Leakage Current	VPGOOD = 5 V	IIOH_PG	-	-	1.0	μA
PGOOD Startup Delay	From end of soft-start (VOUT ramping) until PGOOD asserts	TDH_PD	-	560	720	μs
PGOOD De-Assert (VOUT Falling)	Threshold	VPG_OFF	-	84	-	%VFB
	Accuracy		-2	-	2	
PGOOD Low Voltage	IPGOOD = -4 mA (sinking)	VOL_PG	-	-	0.3	V
PGOOD Shutdown Delay	Falling EN or VFB < POWER_GOOD_OFF until PGOOD de-asserts	TDL_PD	-	2	5	μs

## AUTO RESTART

Automatic-Restart (Hiccup) Delay Time	Setting	THCP	-	32	-	ms
	Accuracy		-15	-	20	%

## POWER STAGE

High-Side MOSFET On Resistance	VBST - VPHASE = 5 V	RDS_HI	-	1.8	-	mΩ
Low-Side MOSFET On Resistance	VPVCC = 5 V	RDS_LO	-	0.8	-	mΩ
High-Gate Pull-Up Resistance (Note 7)	VBST - VPHASE = 5 V, IHG = 2 mA (source)	RHG_UP	-	1.5	-	Ω
High-Gate Pull-Down Resistance (Note 7)	VBST - VPHASE = 5 V, IHG = 2 mA (sink)	RHG_DN	-	0.6	-	Ω
Leading Edge Dead Time (Note 7)	SW/PHASE rising, VBST - VPHASE = 5 V	TSWD_UP	-	14	-	ns
Low-Gate Pull-Up Resistance (Note 7)	VPVCC = 5 V, ILG = 2 mA (source)	RLG_UP	-	0.8	-	Ω
Low-Gate Pull-Down Resistance (Note 7)	VPVCC = 5 V, ILG = 2 mA (sink)	RLG_DN	-	0.4	-	Ω
Trailing Edge Dead Time (Note 7)	SW/PHASE falling, VPVCC = 5 V	TSWD_DN	-	9	-	ns
BST Rectifier On Resistance	VPVCC = 5 V, IF = 2 mA	RBST_ON	-	50	-	Ω
BST Rectifier Reverse Leakage Current	VPVCC = 5 V, VPHASE = 25 V	RBST_LKG	-	-	3	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

7. Performance over the indicated operating temperature range by design and/or characterization and may not be production tested.

TYPICAL PERFORMANCE CHARACTERISTICS

(RESULTS USE FIGURE 1 CIRCUIT,  $V_{IN} = 12\text{ V}$ ,  $V_{OUT} = 1.0\text{ V}$ ,  $F_{SW} = 500\text{ KHZ}$ ,  $R_{BST} = 3.3\ \Omega$ ,  $T_A = 25^\circ\text{C}$ , UNLESS OTHERWISE SPECIFIED. L AND  $C_{OUT}$  VALUES (NOTE 8).)

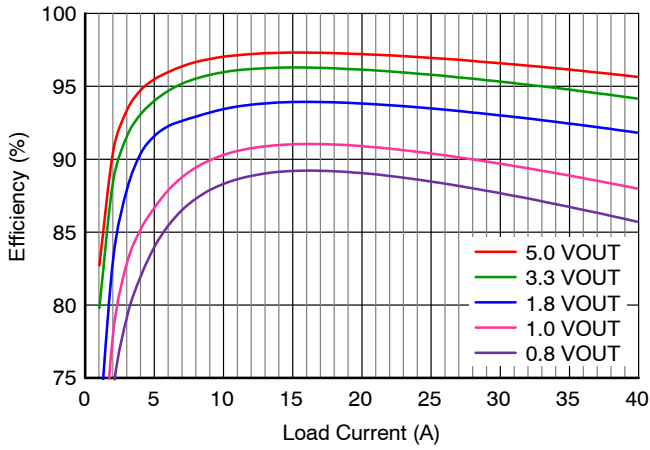


Figure 8. Efficiency vs. Load

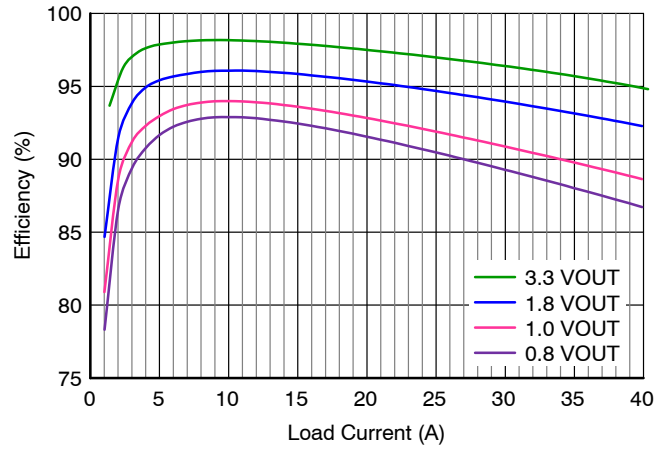


Figure 9. Efficiency vs. Load, 5  $V_{IN}$ ,  $R_{BST} = 0\ \Omega$

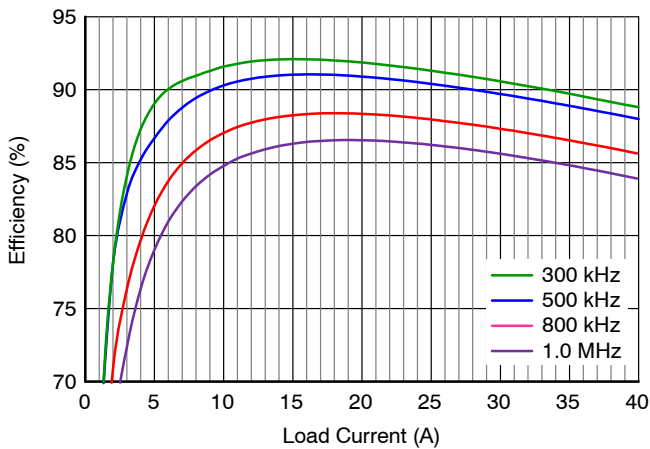


Figure 10. Efficiency vs. Frequency

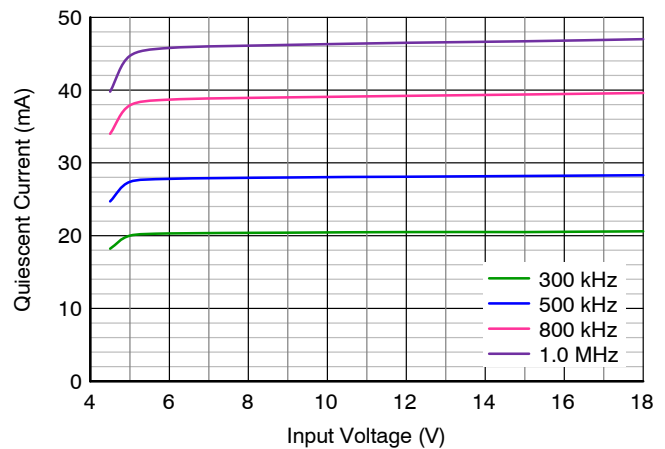


Figure 11. Device Quiescent Current vs.  $V_{IN}$  and Frequency

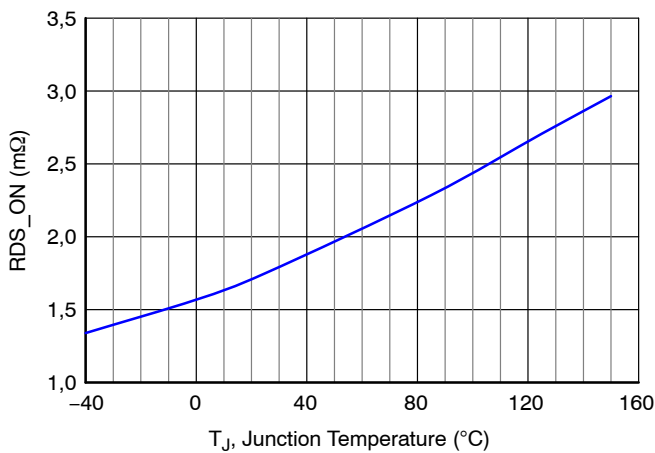


Figure 12. High-Side  $R_{DS\_ON}$  vs. Temperature, 5  $V_{GS}$

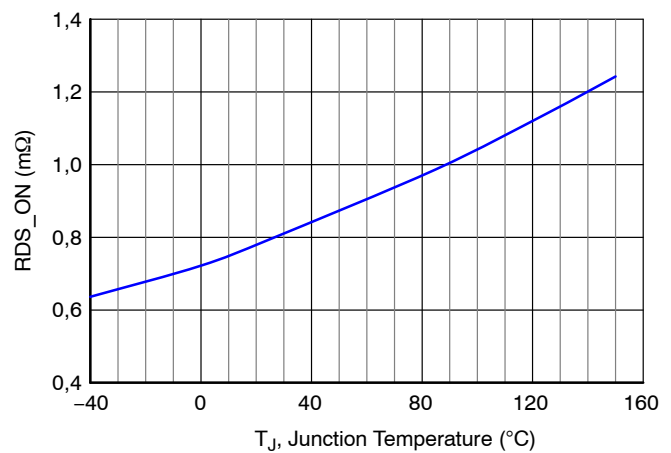


Figure 13. Low-Side  $R_{DS\_ON}$  vs. Temperature, 5  $V_{GS}$

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

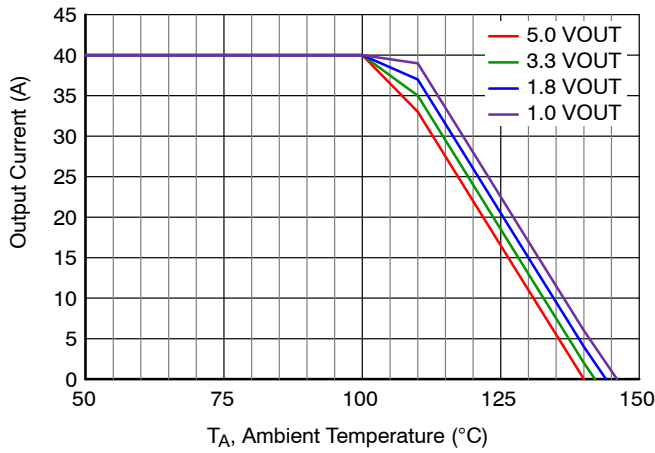


Figure 14. Thermal Safe Operating Area, No Airflow

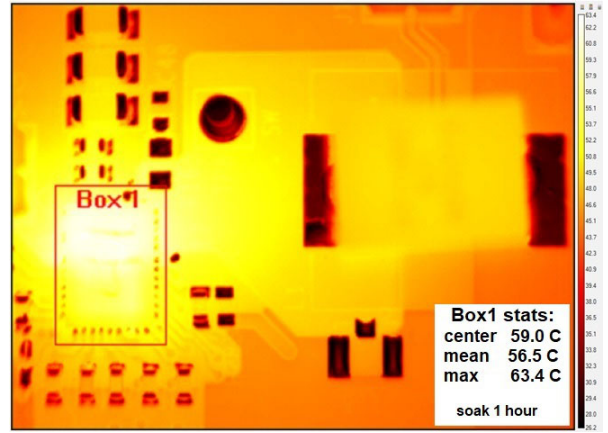


Figure 15. Thermal Image, No Airflow,  $I_{OUT} = 40\text{ A}$

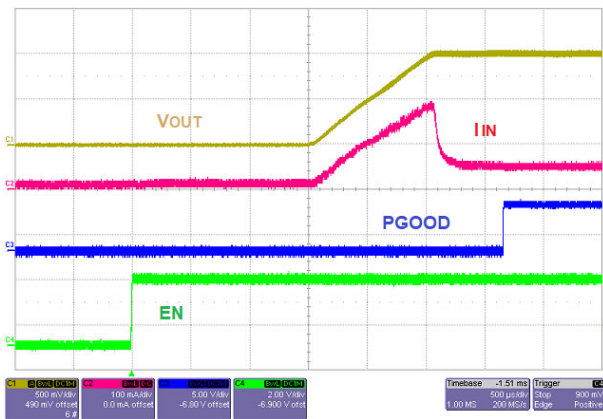


Figure 16. Start-Up, No Load,  $R_{SS/MODE1} = 10\text{ k}\Omega$

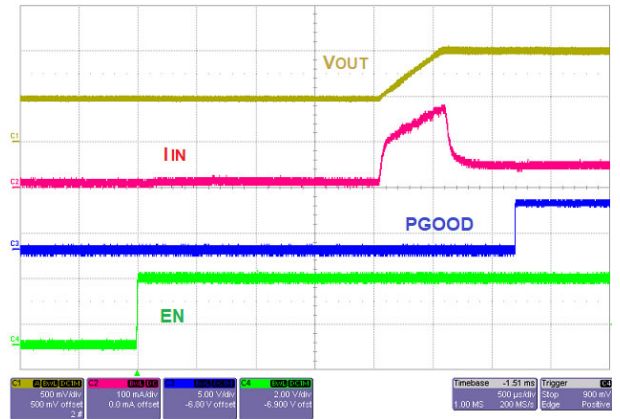


Figure 17. Pre-Bias Start-Up, No Load,  $R_{SS/MODE1} = 10\text{ k}\Omega$

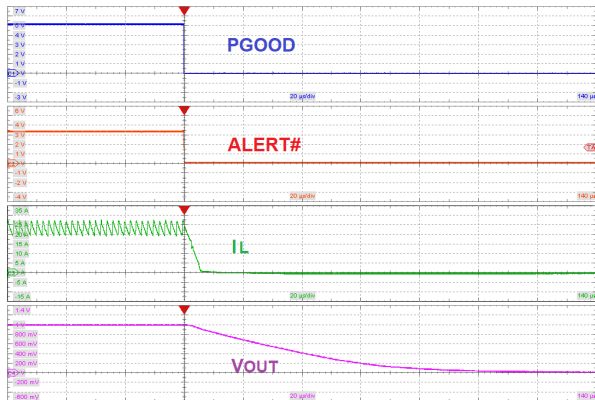


Figure 18. Over-Current Protection Response, Latch-Off,  $I_{LY} = 20\text{ A}$

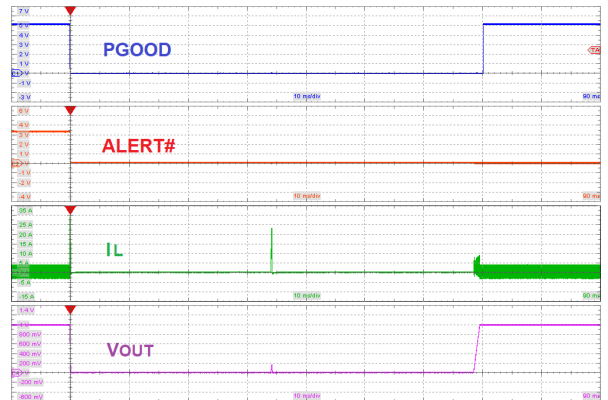


Figure 19. Over-Current Protection Response and Auto-Restart, Hiccup,  $I_{LY} = 20\text{ A}$

# NCP3296

## TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

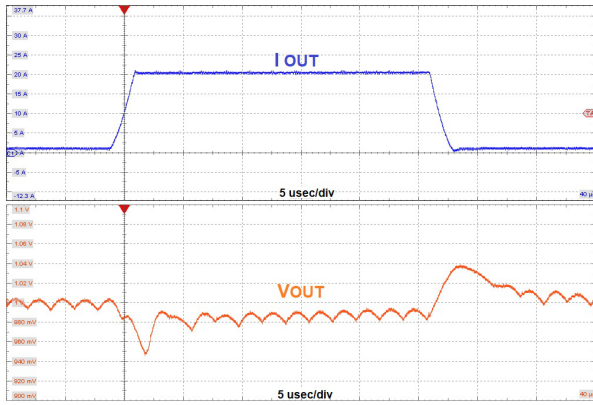


Figure 20. Load Transient Response, 1 – 21 A, 10 A/μs

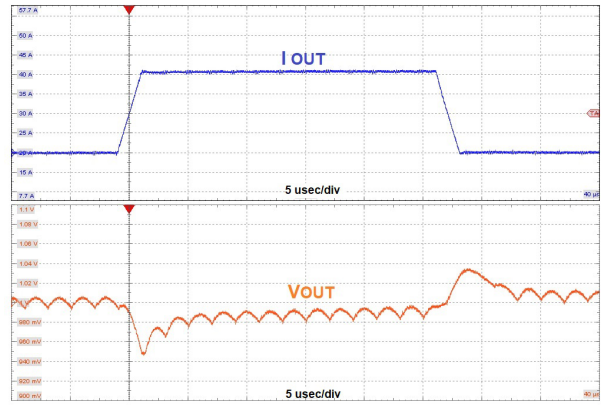


Figure 21. Load Transient Response, 20 – 40 A, 10 A/μs

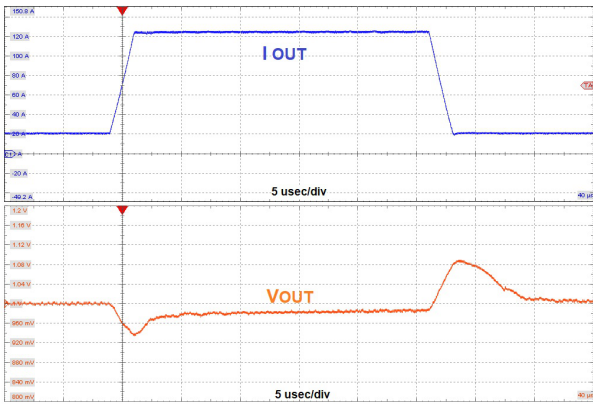


Figure 22. 4-Phase Load Transient Response, 20 – 125 A, 50 A/μs

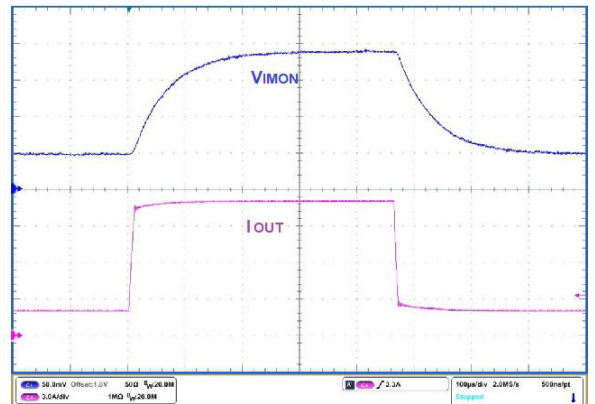


Figure 23. Dynamic IMON Tracking, 3 – 11 A, 1 A/μs

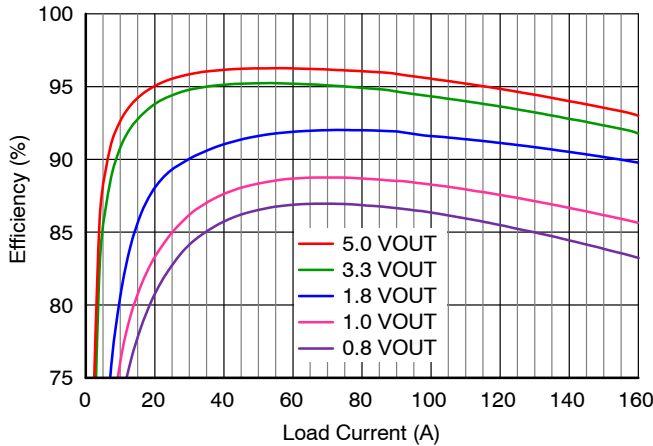


Figure 24. Efficiency vs. Load, 4-Phase

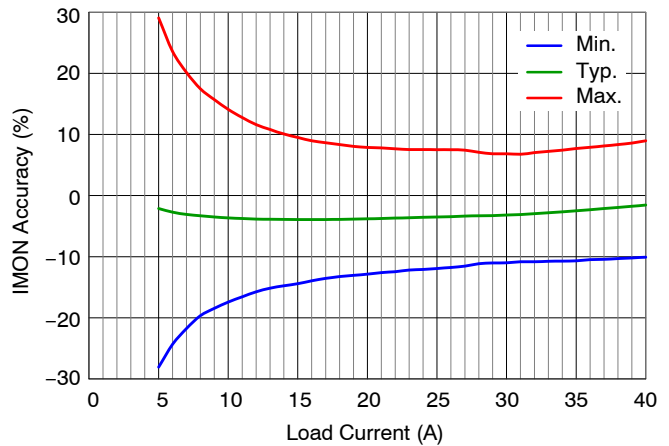


Figure 25. IMON Accuracy vs. Load

NOTE:

8.  $C_{OUT}$  used for testing:

Phases	Capacitance
1	20  22 μF ceramic + 2  470 μF poscap
4	20  22 μF ceramic + 6  470 μF poscap

L used:

$V_{OUT}$	L (nH)	DCR (μΩ)
<1.5	210	290
1.8	330	155
3.3	560	1,400
5.0	1,000	2,300

Supplier
Eaton FP1108R1-R21-R
Würth 744305033
Würth 744373770056
Pulse PA4343.102NLT

APPLICATION INFORMATION

**General**

The NCP3296, a highly efficient stackable synchronous buck regulator, is capable of operating over an input voltage range of 3.0 V to 18 V, supporting load currents up to 40 A. Higher output currents can be achieved by paralleling up to four NCP3296 devices.

The NCP3296 employs a fixed frequency current mode control scheme to provide accurate voltage regulation and fast transient response. Flexible programmability of function and parameters support multiple applications.

**V<sub>OUT</sub> Scale Loop Setting**

For V<sub>OUT</sub> Scale other than 1, a resistor divider of equivalent ratio is required from V<sub>OUT</sub> to FB to VSNS-.

Using Table 2, select the value (R<sub>PIN</sub>) for R<sub>SS/MODE1</sub> corresponding to the desired V<sub>OUT</sub> Scale level and soft-start time (T<sub>SS</sub>).

**V<sub>OUT</sub> Setting**

Use Table 2 to select the value (R<sub>PIN</sub>) for R<sub>VSET/FAULT</sub> corresponding to the desired V<sub>OUT</sub> level for the previously established V<sub>OUT</sub> Scale setting.

**Setting Frequency**

Use Table 2 to select the value (R<sub>PIN</sub>) for R<sub>SYNC/FSET</sub> associated with the desired switching frequency per phase and the total number of phases to be implemented.

**Current Limit Setting**

The per phase current limit setting (I<sub>VLY</sub>) and protection mode (hiccup/latch-off) are established by R<sub>IMON/ILIM</sub>, according to the R<sub>PIN</sub> value (R<sub>PIN</sub>) shown in Table 2.

**Master/Slave Configuration**

The NCP3296 can be configured as either a master or slave in an interleaved, multi-phase POL system, by its FB and VSNS- pin configuration, as shown in Table 1.

**Table 1. MASTER/SLAVE CONFIGURATION**

	FB	VSNS-	Application
Master	V <sub>OUT</sub>	GND	1, 2, 3, 4 phase
1 <sup>st</sup> Slave	VCC	GND	2, 3, 4 phase
2 <sup>nd</sup> Slave	VCC	VCC	3, 4 phase
3 <sup>rd</sup> Slave	VCC	100 kΩ – GND	4 phase

**Operation Modes**

Device operating mode is determined by 1% resistor selection (R<sub>PIN</sub>) at the appropriate device pin, as shown in Table 2.

**Table 2. OPERATING MODE SELECTION**

R <sub>PIN</sub> (kΩ)	R <sub>VSET/FAULT</sub> Pin			R <sub>SS/MODE1</sub> Pin		R <sub>IMON/ILIM</sub> Pin	R <sub>MODE2/SFAULT</sub> Pin		R <sub>SYNC/FSET</sub> Pin			
	Set V <sub>OUT</sub>			Set V <sub>OUT</sub> Scale and Soft-Start Time (T <sub>SS</sub> )		Set Current Limit (I <sub>VLY</sub> ), per Phase	Set Phase Count and Protection Mode		Set Frequency (F <sub>sw</sub> ), per Phase			
	1 Scale (V)	1/2 Scale (V)	1/4 Scale (V)	T <sub>SS</sub> (ms)	V <sub>OUT</sub> -Scale (N)	I <sub>LIM</sub> (A)	Phases (N)	Mode	1φ (kHz)	2φ (kHz)	3φ (kHz)	4φ (kHz)
10.0	0.50	1.30	2.40	1	1	10	1 phase (1φ)	Hiccup	200	200	200	200
15.0	0.55	1.35	2.50	3		12			250	250	250	250
18.2	0.60	1.40	2.60	5		14		Latch-Off	300	300	300	300
22.1	0.65	1.45	2.70	10		16			350	350	350	350
27.4	0.70	1.50	2.80	15		18		2 phase (2φ)	Hiccup	400	400	400
33.2	0.75	1.55	2.90	1	20	500	450			450	450	
39.2	0.80	1.60	3.00	3	24	Latch-Off	600		500	500	500	
47.5	0.85	1.65	3.10	5	28		700		550	550		
56.2	0.90	1.70	3.20	10	32	3 phase (3φ)	Hiccup		800	600	600	
68.1	0.95	1.75	3.30	15	36			900	650	650		
82.5	1.00	1.80	3.40	1	40		Latch-Off	1,000	700			
100	1.05	1.90	3.50	3	44			1,200	750			
121	1.10	2.00	4.00	5	48		4 phase (4φ)	Hiccup	1,400	800		
150	1.15	2.10	4.50	10	52	1,600			850			
182	1.20	2.20	5.00	15	56	Latch-Off		1,800	900			
221	1.25	2.30	5.50	20	60			2,000	1,000			

The use of substitute resistor values is not recommended.



**Soft Start**

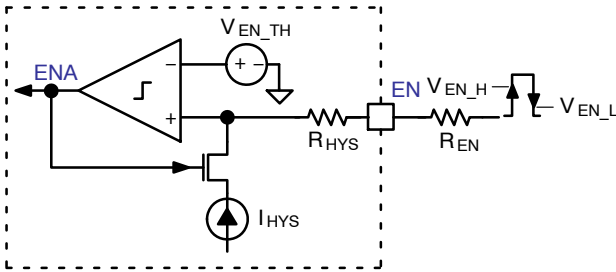
The NCP3296 soft-start function allows starting into a pre-biased output. When the device is enabled, the soft-start ramp time ( $T_{SS}$ ) begins after a fixed delay ( $T_{ON\_DLY}$ ).

During the soft-start ramp, switching is prevented when pre-biased  $V_{FB}$  exceeds the target reference voltage. At the end of soft-start, if  $V_{FB}$  continues to be greater than the programmed reference level, switching will commence to bring the output into compliance.

When the device is disabled, or at falling UVLO, the device shuts down immediately and the power MOSFETs are forced off.

**Enable**

The NCP3296 is enabled when the rising EN voltage ( $V_{EN\_H}$ ) exceeds  $V_{EN\_TH}$ , as illustrated below:

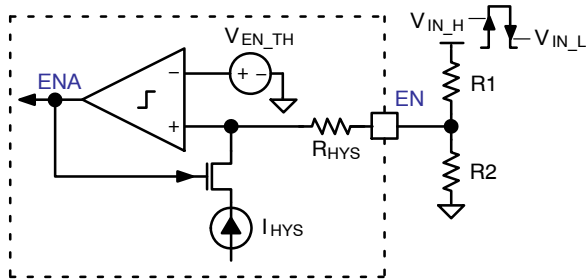


**Figure 26. Enable Thresholds and Hysteresis**

Optional  $R_{EN}$  can be added externally to increase the amount of hysteresis to reach the falling threshold. The falling threshold can be calculated by:

$$V_{EN\_L} = V_{EN\_TH} - I_{HYS} \cdot (R_{HYS} + R_{EN}) \quad (\text{eq. 1})$$

The EN pin can also be used to implement an input supply UVLO function using the circuit below:



**Figure 27. EN Pin Input UVLO Circuit**

The associated rising and falling  $V_{IN}$  thresholds are:

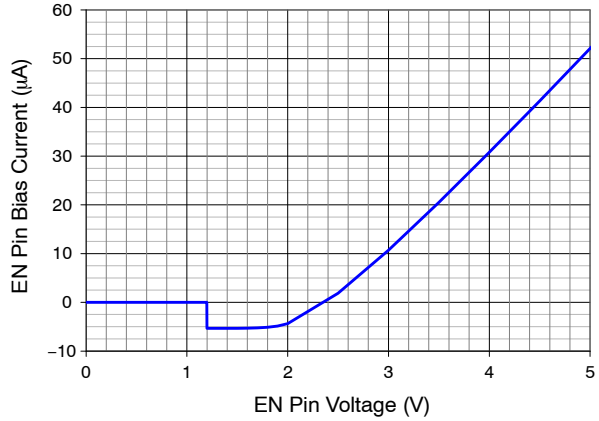
$$V_{IN\_H} = V_{EN\_TH} \cdot \left( \frac{R1}{R2} + 1 \right) \quad (\text{eq. 2})$$

$$V_{IN\_L} = K + R1 \cdot \left( \frac{K}{R2} - I_{HYS} \right) \quad (\text{eq. 3})$$

where:

$$K = V_{EN\_TH} - I_{HYS} \cdot R_{HYS} \quad (\text{eq. 4})$$

To avoid unintended or undefined operation, the EN pin should not be left floating in the application.



**Figure 28. Typical EN Pin Bias Current**

**Over-Current Protection (OCP)**

The NCP3296 employs a cycle-by-cycle valley current limit ( $I_{VLY}$ ) threshold to protect the regulator. The average current limit ( $I_{LIM}$ ) value can be calculated from the inductor ripple current and  $I_{VLY}$  using:

$$I_{LIM} = I_{VLY} + \frac{V_{OUT} \cdot (V_{IN} - V_{OUT})}{2 \cdot V_{IN} \cdot L \cdot F_{SW}} \quad (\text{eq. 5})$$

OCP detection starts at the beginning of the soft-start ramp ( $T_{SS}$ ) and extends until shutdown. Inductor current is monitored between SW and PGND. If the OCP event lasts for more than 32 consecutive switching cycles, the device enters fault state (hiccup or latch-off). If  $V_{OUT}$  is falling rapidly, the device may trip under-voltage protection before the 32 current limit cycles accumulate.

To restart the device from an OCP latch-off condition, the system needs to toggle VCC or EN off, then back on.

**Output Under-Voltage Protection (UVP)**

UVP detection is active from when PGOOD asserts at the end of soft-start, until shutdown. The NCP3296 will force PGOOD low and turn off both power MOSFETs once the FB pin voltage falls below  $V_{UVP\_TH}$  threshold for more than  $T_{D\_UVP}$ .

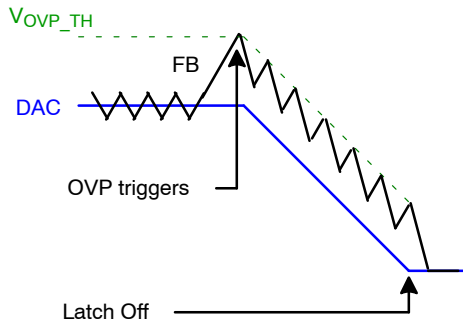
To restart the device after a UVP latch-off, the system needs to toggle VCC or EN off, and then back on.

**Output Over-Voltage Protection (OVP)**

The NCP3296 offers output over-voltage protection to protect the regulator and prevent the possible destruction of the downstream load. OVP is active from the beginning of soft-start until shutdown, latch-off, or during hiccup idle time.

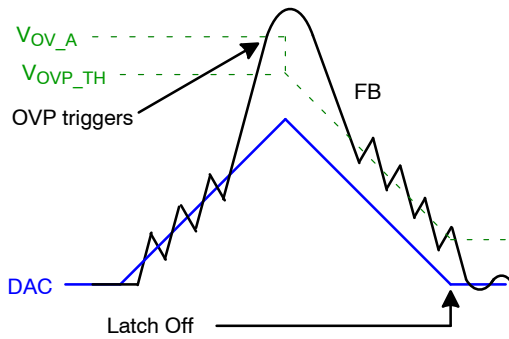
During operation, if the FB pin voltage exceeds the  $V_{OVP\_TH}$  threshold for longer than  $T_{D\_OVP}$ , OVP is triggered and PGOOD is forced low.

Once OVP triggers, FCCM operation is maintained while the DAC voltage ramps down at the  $T_{OFF}$  rate, preventing large negative voltage spikes from occurring at the output. Once the DAC reaches 0, the high-side FET is turned off, while the low-side FET remains on.



**Figure 29. OVP Behavior during Normal Operation**

During soft-start, the OVP threshold is set to a fixed absolute value of  $V_{OV\_A}$ .



**Figure 30. OVP Behavior during Start-Up**

To restart the device after an OVP latch-off, the system needs to toggle VCC or EN off, and then back on.

**Thermal Shutdown ( $T_{SD}$ )**

Severe overheating is prevented by forcing the entire device into shutdown when die temperature ( $T_J$ ) reaches the thermal shutdown threshold ( $T_{SD}$ ).  $T_{SD}$  detection activates when VCC and EN are valid. Once the thermal protection is triggered, the entire chip remains off until  $T_J$  cools to  $T_{RST}$ , where an automatic recovery and soft-start sequence commence.

**Input Over-Voltage Protection ( $V_{IN}$  OVP)**

When the input voltage, measured at the PVIN pin, exceeds the  $V_{PVIN\_OVP}$  threshold for the de-bounce time of  $T_{D\_VINOV}$ , the device enters fault state and switching ceases.

Once the input voltage falls below  $V_{PVIN\_OVP} - V_{PVIN\_HYS}$ , an automatic restart occurs after a fixed 32 ms delay.

**Hiccup / Latch-Off Mode**

The selected resistor value at the MODE2/SFAULT pin ( $R_{MODE2/SFAULT}$ ) determines whether hiccup or latch-off protection mode is applied under  $V_{OUT}$  OVP,  $V_{OUT}$  UVP, or OCP conditions.

To restart a device in latch-off mode, EN or VCC need to be toggled. In hiccup mode, the idle time counter ( $T_{HCP}$ ) begins counting when the device shuts down for OCP, UVP, or the end of OVP DAC ramp down. A normal start-up sequence automatically occurs once  $T_{HCP}$  expires.

**PGOOD Pin**

The PGOOD signal is held low during soft-start and in shutdown state.

PGOOD is high while  $V_{FB}$  remains within the adjustable regulation envelope determined by the  $V_{OVP\_TH}$  and  $V_{UVP\_TH}$  thresholds.

During thermal shutdown ( $T_{SD}$ ), PGOOD is low until the device sufficiently cools. PGOOD will be low during all fault conditions.

**Multi-Phase Frequency and Synchronization**

Per phase switching frequency ( $F_{SW}$ ) and phase count (N) are programmed by  $R_{SYNC/FSET}$  and  $R_{MODE2/SFAULT}$  resistor value selections per Table 2. The sequential interleave order of the slave phases is determined by FB and VSNS- pin connections shown in Table 1.

In a multi-phase system, the master outputs a SYNC signal to the parallel slaves' SYNC pins to establish a common switching frequency and evenly space the interleaved phases, as shown in the subsequent figure:

The falling edge of the SYNC pulse resets the ramp, beginning the interleaved PWM on cycles after a narrow propagation delay. The vertical dotted lines signify the modulated PWM edge (duty cycle).

# NCP3296

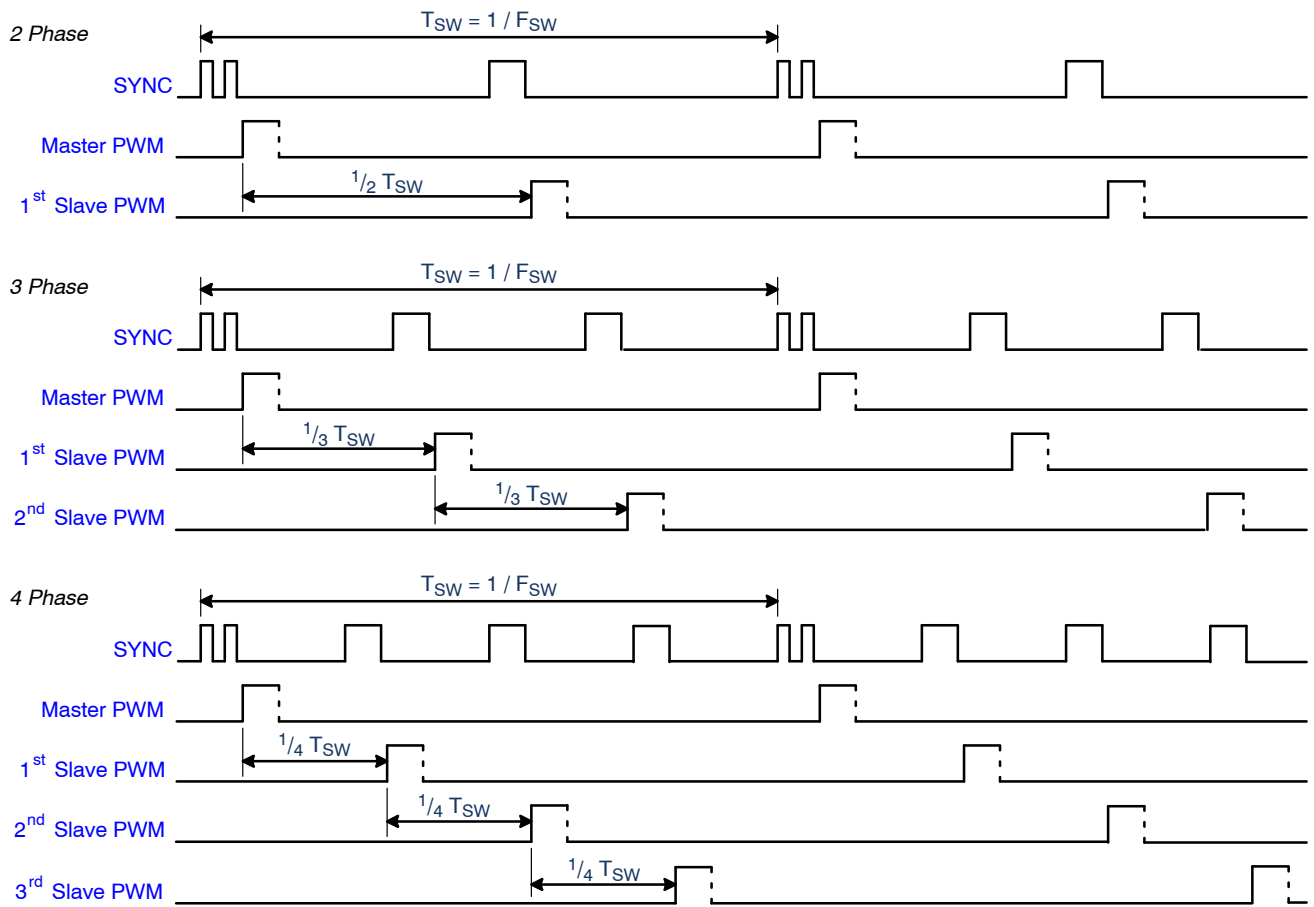


Figure 31. Multi-Phase Synchronization Timing

**FAULT and SFAULT Operation**

In a multi-phase application, communication between the master and slaves is accomplished via signaling over the VSET/FAULT and MODE2/SFAULT pins.

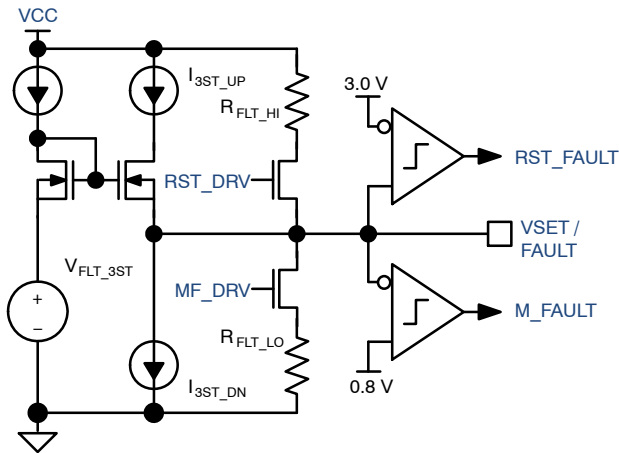
The following table is a summary of NCP3296 actions in response to the main fault conditions:

**Table 3. MASTER / SLAVE ACTIONS BY PROTECTION TYPE**

Master / Standalone		Protection Type	Slave	
Detection	Action		Detection	Action
V <sub>CC</sub>	Auto recoverable Both power MOSFETS off FAULT pulled high SFAULT pulled low	UVLO	V <sub>CC</sub>	Auto recoverable Both power MOSFETS off FAULT pulled high SFAULT pulled low
T <sub>J</sub>	Auto recoverable Both power MOSFETS off FAULT pulled low	TSD	T <sub>J</sub>	Auto recoverable Both power MOSFETS off SFAULT pulled low
I <sub>DRAIN</sub>	Cycle-by-cycle current limit Both power MOSFETS off FAULT pulled low	OCP	I <sub>DRAIN</sub>	Cycle-by-cycle current limit Both power MOSFETS off SFAULT pulled low
V <sub>FB</sub>	Both power MOSFETS off FAULT pulled low	UVP	Master V <sub>FB</sub>	Both power MOSFETS off after Master pulls FAULT low
V <sub>FB</sub>	Ramp down DAC with FCCM High-side FET turns off Low-side FET remains on SFAULT pulled high	OVP	Master V <sub>FB</sub>	Once Master pulls SFAULT high: High-side FET turns off Low-side FET remains on

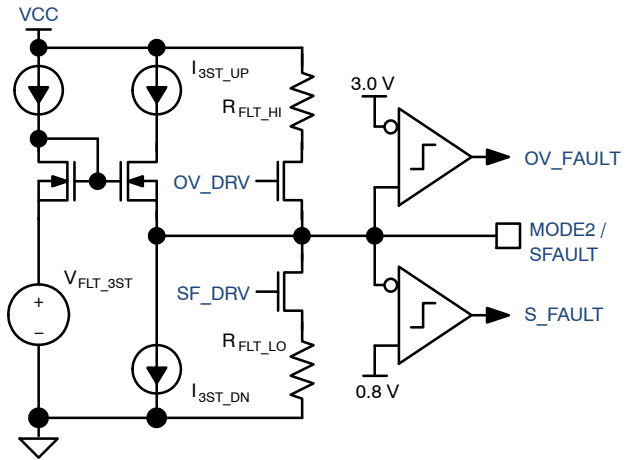
**FAULT and SFAULT Signaling**

The VSET/FAULT and MODE2/SFAULT pins utilize bi-directional signaling for master/slave communication and fault management. The figures below illustrate how the circuit works:



**Figure 32. VSET/FAULT Pin Circuit**

The internal signal MF\_DRV asserts high when a master fault occurs. RST\_DRV gets asserted to reset the system. M\_FAULT and RST\_FAULT are the associated fault signals (active high).

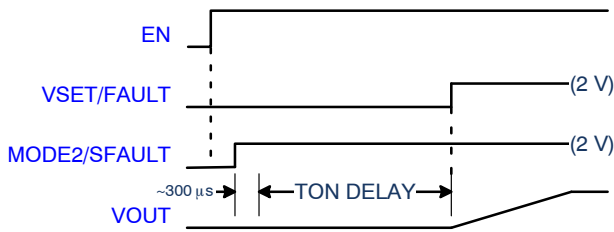


**Figure 33. MODE2/SFAULT Pin Circuit**

The internal signal OV\_DRV asserts when the master detects an output OVP event, which forces the MODE2/SFAULT pin high. SF\_DRV asserts when a slave needs to signal a fault condition. OV\_FAULT and S\_FAULT are the associated fault signals (active high).

When EN=0, the master forces both VSET/FAULT and MODE2/SFAULT low. Switching is prohibited.

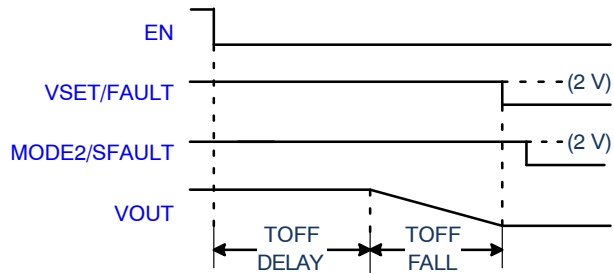
The VSET/FAULT and MODE2/SFAULT signals remain tri-stated (2 V) during normal operation.



**Figure 34. Master/Slave Start-Up Signals**

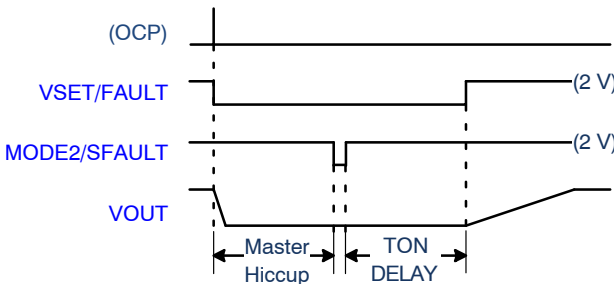
At start-up, once EN is asserted, the master imposes a small housekeeping delay before tri-stating the MODE2/SFAULT pin, which awakens the slaves. While VSET/FAULT is low, all the master and slave FETs remain off.

After the TON\_DELAY period expires, the master tri-states the VSET/FAULT pin and the soft-start cycle begins.



**Figure 35. Master/Slave Power-Off Signals**

When EN goes low, the VSET/FAULT and MODE2/SFAULT pins remain tri-stated until the TOFF\_DELAY and TOFF\_FALL intervals expire. Then, the master lowers the VSET/FAULT pin which halts switching and all FETs are turned off. Later, the master lowers the MODE2/SFAULT pin, returning the slaves to their stand-by (inactive) state.



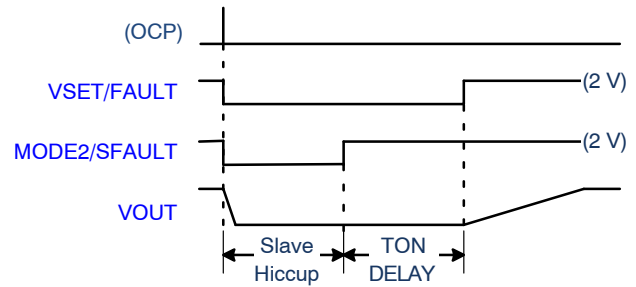
**Figure 36. Master/Slave Signals, Master OCP or UVP**

When the master encounters an over-current fault situation, indicated here by internal logic signal (OCP) high, it lowers the VSET/FAULT pin to instruct slaves to stop switching.

Once the master completes its hiccup cycle, it momentarily cycles MODE2/SFAULT low to reset and re-activate slaves.

Upon expiration of the TON\_DELAY interval, the master tri-states the VSET/FAULT pin and a soft-start cycle commences.

The same signaling/sequence is used in response to output under-voltage (UVP) faults.

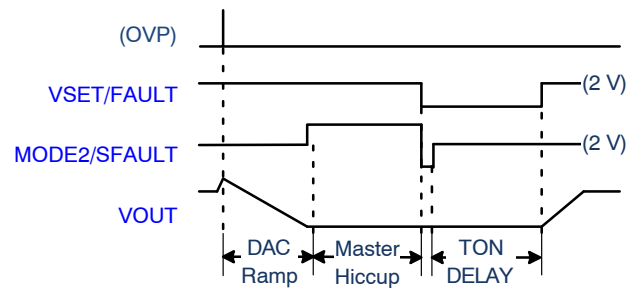


**Figure 37. Master/Slave Signals, Slave OCP or OT Fault**

When any slave encounters an over-current event, it signals the master by lowering the MODE2/SFAULT pin. As a result, the master forces VSET/FAULT low to halt all switching.

Once the slave hiccup period expires, it releases the MODE2/SFAULT signal. The master holds VSET/FAULT low to prevent all switching until TON\_DELAY elapses. When the master releases the VSET/FAULT signal to the tri-state level, the soft-start cycle commences.

The same signaling/sequence is used in response to an over-temperature (OT) fault.



**Figure 38. Master/Slave Signals, OVP Fault**

In the event of an output over-voltage fault (OVP), the VSET/FAULT and MODE2/SFAULT pins both remain at 2 V until the DAC ramps down the output in a controlled fashion.

During the hiccup interval, the master pulls MODE2/SFAULT high, instructing the slaves to turn off high-side FETs and enhance low-side FETs.

After the hiccup cycle, the master forces both signals low, momentarily, which resets the slaves. Slaves re-activate when the master releases the MODE2/SFAULT signal during the TON\_DELAY interval. When the master releases the VSET/FAULT signal, the re-start ramp begins.

**Operating / Fault States**

The table below provides a summary of device and pin states during operating and/or fault conditions:

**Table 4. STATE TRUTH TABLE**

State / Condition	Action / Function				
	PGOOD Pin	COMP Pin	OCP	OVP	UVP
<b>POR</b> $V_{CC} < UVLO$	N/A	N/A	N/A	N/A	N/A
<b>Disabled</b> , EN low, $V_{CC} > UVLO$	Low	Low	Disabled	Disabled	Disabled
<b>Start-Up Delay</b> EN low, $V_{CC} > UVLO$ , before SS ramp begins	Low	Low	Disabled	Disabled	Disabled
<b>Soft Start</b> EN high, $V_{CC} > UVLO$	Low	Active	Active	Active, (threshold = $V_{OV\_A}$ )	Disabled
<b>Normal Operation</b>	High	Active	Active	Active, (threshold = $V_{OVP\_TH}$ )	Active
<b>Over-Current (OCP)</b>	Low		Cycle-by-Cycle	Active until shutdown	Active until shutdown
<b>Over-Voltage (OVP)</b>	Low		Disabled		Disabled
<b>Under Voltage (UVP)</b>	Low		Disabled	Disabled	
<b>Thermal Shutdown (Tsd)</b>	Low	Low	Disabled	Disabled	Disabled
<b>Hiccup Idle Time</b>	Low	Low	Disabled	Disabled	Disabled

## PCB LAYOUT GUIDELINE

Good electrical layout is key to ensure proper operation, high efficiency, and noise reduction.

- **Bias Decoupling:** Place the decoupling caps as close as possible to the controller's VCC and VDRV pins. The VCC pin filter resistor should be  $\leq 2.2 \Omega$  to prevent a large voltage drop.
- **Input Supply Decoupling:** Place and route the input capacitors to maintain the shortest possible current loop length to reduce parasitic inductance, input voltage spikes, and noise emission. Commonly, a low ESL MLCC capacitor is placed adjacent to the PVIN and PGND pins for high frequency noise reduction.
- **Power Paths:** Use the widest and shortest possible traces for high current paths such as PVIN, VOUT, SW, and PGND to minimize series ESL and ESR. ESR contributes to power losses and temperature rise.
- **Switching Node:** The SW, PHASE, and BST pins contain high-voltage discontinuous switching waveforms with sharp edges. Care should be taken to avoid capacitive coupling to sensitive signals like FB, VSNS-, and COMP. Avoid routing these sensitive signals adjacent to or over/under on adjacent layers without GND shields, to the discontinuous switching signals.  
It is recommended to add RC snubber component locations to the PCB design should these be required to provide additional damping for peak SW voltages. The snubber devices should be placed adjacent to the IC, between SW and GND.
- **Bootstrap:** The bootstrap capacitor ( $C_{BST}$ ) and series resistor ( $R_{BST}$ ) should be connected directly between the BST and PHASE pins using a low impedance path. It is not necessary to establish a connection between PHASE and SW, as this is already accomplished within the IC. The series resistor is used for limiting peak SW voltages

to safe levels, particularly at elevated  $V_{IN}$  levels.  $R_{BST}$  works similar to a RC snubber by slowing the switching edges, which may also be used, although either can negatively impact efficiency.

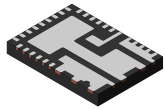
- **Voltage Sense:** Use a Kelvin sense pair to route from the FB and VSNS- pins to the remote sense point. The pair is best routed over solid GND plane, if possible. Avoid routing adjacent to switching nodes or other noise sources.
- **Compensation Network:** All components of the RC network connected to FB and COMP should be placed as close as possible to the IC pins with care to avoid routing traces adjacent to noise sources.
- **Ground:** Directly connect the exposed PGND pad to the GND plane using multiple vias. The use of multiple system GND planes is recommended. Connect AGND pin to the system GND plane at a single location, near the IC's AGND pin, using a robust, low impedance path.
- **Master/Slave Signals:** In a multi-phase/stacked system, master and slave interconnections should be routed using low impedance traces avoiding switching noise sources. This is particularly important for the COMP signal.
- **Thermal Layout Considerations:**  
Ensure the large exposed pad (DAP) under the IC, is securely soldered.  
Improved heat spreading can be achieved by using multiple GND layers with liberally applied thermal vias around the IC connected to those GND planes.  
Use large copper pours (areas), where possible, to improve thermal conduction and radiation.  
Keep the inductor away from the IC to distribute heat sources and reduce vicinity heating.

## ORDERING INFORMATION

Device	Current	Package	Shipping†
NCP3296MNTXG	40 A	WQFN34, 5 x 7 mm (Pb-Free)	3000 units / Tape & Reel

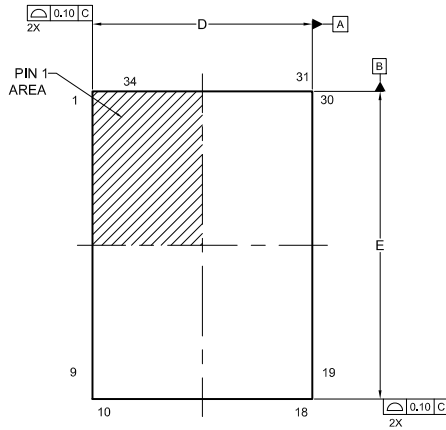
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

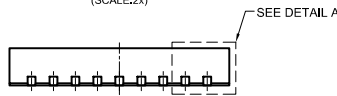


## WQFN34 5.00x7.00x0.75, 0.50P CASE 510CL ISSUE C

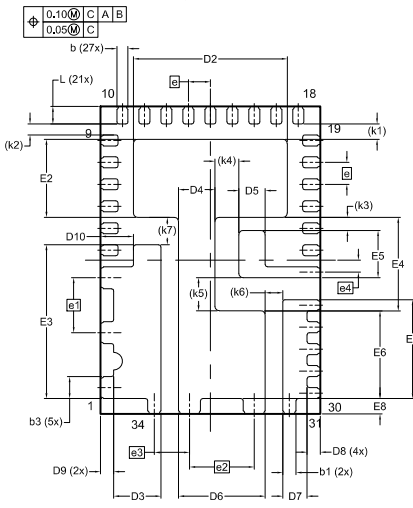
DATE 03 APR 2024



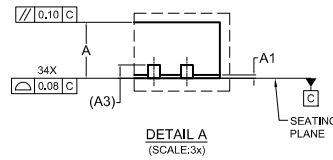
TOP VIEW  
(SCALE:2x)



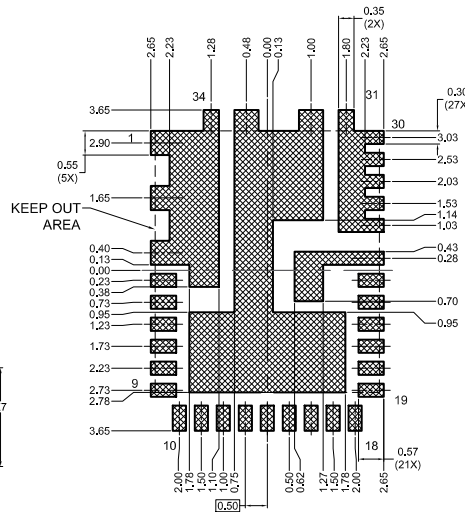
FRONT VIEW  
(SCALE:2x)



BOTTOM VIEW  
(SCALE:2x)



DETAIL A  
(SCALE:3x)



LAND PATTERN  
RECOMMENDATION

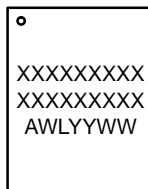
\*FOR ADDITIONAL INFORMATION ON OUR  
PB-FREE STRATEGY AND SOLDERING DETAILS,  
PLEASE DOWNLOAD THE ON SEMICONDUCTOR  
SOLDERING AND MOUNTING TECHNIQUES  
REFERENCE MANUAL, SOLDERRM/D.

NOTES: UNLESS OTHERWISE SPECIFIED

- A) DOES NOT FULLY CONFORM TO JEDEC REGISTRATION MO-220, DATED MAY/2005.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	--	0.50
A3	0.20 REF		
b	0.20	0.25	0.30
b1	0.25	0.30	0.35
b2	0.40	0.50	0.60
D	4.90	5.00	5.10
D2	3.40	3.50	3.60
D3	0.98	1.08	1.18
D4	0.73	0.83	0.93
D5	0.50	0.60	0.70
D6	1.87	1.97	2.07
D7	0.45	0.55	0.65
D8	0.20	0.30	0.40
D9	0.20	0.30	0.40
D10	0.65	0.75	0.85
E	6.90	7.00	7.10
E2	1.68	1.78	1.88
E3	3.40	3.50	3.60
E4	2.03	2.13	2.23
E5	0.98	1.08	1.18
E6	1.89	1.99	2.09
E7	2.15	2.25	2.35
E8	0.25	0.35	0.45
e	0.50 BSC		
e1	1.25 BSC		
e2	1.50 BSC		
e3	0.80 BSC		
e4	0.275BSC		
k1	0.35 REF		
k2	0.25 REF		
k3	0.30 REF		
k4	0.54 REF		
k5	0.75 REF		
k6	0.40 REF		
k7	0.63 REF		
L	0.30	0.40	0.50

### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WQFN34 5.00x7.00x0.75, 0.50P	PAGE 1 OF 1

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